

REMARKS

The Office action of May 25, 2005, has been carefully considered.

Objection has been raised to the specification based on the word "dies" on page 1, and the specification has now been amended to correct this error.

Claims 1 and 4 have been rejected under 35 U.S.C. 102(e) as anticipated by Reeh et al, while Claims 2 and 3 have been rejected under 35 U.S.C. 103(a) as unpatentable over Reeh et al in view of Bogner et al.

According to Claim 1 as amended, the substrate has a flat upper surface and an LED is mounted on this upper surface of the substrate. A first transparent layer is mounted on the substrate for sealing the LED and a second transparent layer having an underside surface, co-extensive with (of the same shape and size as) the upper surface of the substrate is mounted on the upper surface of the substrate so as to surround the first transparent layer. Fluorescent material and coloring agent are included in the second transparent layer, and a reflector layer is formed on peripheral outside walls of the second transparent layer, except for the upper side of the second transparent layer. This arrangement is not disclosed or suggested by the cited references.

The cited embodiment of Reeh et al, Figure 3, discloses an arrangement in which neither of the layers actually seals the LED. It is noted that element 9 is alleged in the Office action to be a "second transparent layer" but is rather a recess, as disclosed in the specification in paragraph [0092]. While layer 4 may be a transparent layer, it does not actually seal the LED, but rather only covers the recess. If there is a structure in Reeh et al corresponding to a second transparent layer, it is base housing 8, which surrounds the

recess. Moreover, the recess 9 is designed as a reflector 17 for radiation emitted by the semiconductor body, and the reflector layer is therefore not formed on peripheral outside walls of the second transparent layer, but rather in the walls themselves.

Finally, according to Reeh et al, the substrate does not have a flat upper surface since terminals 2 and 3 project from the upper surface of the substrate.

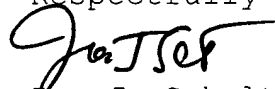
While Bogner et al has been cited to show the use of fluorescent materials and coloring agents, Bogner et al does not otherwise cure the defects of the Reeh et al reference.

Thus, the references taken as a whole do not disclose or suggest a substrate having a flat upper surface with an LED mounted on the upper surface, a first transparent layer mounted on the substrate for sealing the LED and a second transparent layer mounted on the upper surface surrounding the first transparent layer, and being coextensive with the upper surface, with fluorescent materials and particles of coloring agent included in the second transparent layer, and a reflector layer formed on peripheral outside walls of the second transparent layer. This claimed structure enables a plurality of devices to be manufactured simultaneously as described in the specification, and the consequent low cost of manufacture of these devices.

Withdrawal of these rejections is requested.

In view of the foregoing amendments and remarks, Applicant submits that the present application is now in condition for allowance. An early allowance of the application with amended claims is earnestly solicited.

Respectfully submitted,



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